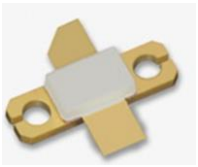
Gallium Nitride 28V 60W, RF Power Transistor

Description

The GTAH35060GX is a 60W internally matched, GaN HEMT, designed for multiple applications, especially sub-6GHz MC-GSM/WCDMA/LTE/LTE-A from 700-3800MHz.

There is no guarantee of performance when this part is used in applications designed Outside of these frequencies.

GTAH35060GX



Applications and Features

- Suitable for wireless communication infrastructure, wideband amplifier, EMC testing, ISM etc.
- High Efficiency and Linear Gain Operations
- Thermally Enhanced Industry Standard Package
- High Reliability Metallization Process
- Excellent thermal Stability and Excellent Ruggedness
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

1. Set VGS to the pinch--off (VP) voltage, typically –5 V
2. Turn on VDS to nominal supply voltage (28V)
3. Increase VGS until IDS current is attained
4. Apply RF input power to desired level

Turning the device OFF

1. Turn RF power off
2. Reduce VGS down to VP, typically –5 V
3. Reduce VDS down to 0 V
4. Turn off VGS

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain--Source Voltage	V_{DSS}	150	Vdc
Gate--Source Voltage	V_{GS}	-10,+2	Vdc
Operating Voltage	V_{DD}	40	Vdc
Maximum Forward Gate Current @ T_C = 25°C	Igmax	14	mA
Storage Temperature Range	T_{stg}	-65 to +150	°C
Case Operating Temperature	T_C	+150	°C
Operating Junction Temperature(See note 1)	T_J	+200	°C
Total Device Power Dissipation (Derated above 25°C, see note 2)	Pdiss	70	W

Note: 1. Continuous operation at maximum junction temperature will affect MTTF
2.Bias Conditions should also satisfy the following expression: Pdiss < (Tj – Tc) / RJC and Tc = Tcase

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case T_C= 85°C, T_J=200°C, RF CW operation	$R_{\theta JC}$	2.52	C/W

Table 3. Electrical Characteristics (T_C = 25℃ unless otherwise noted)

DC Characteristics

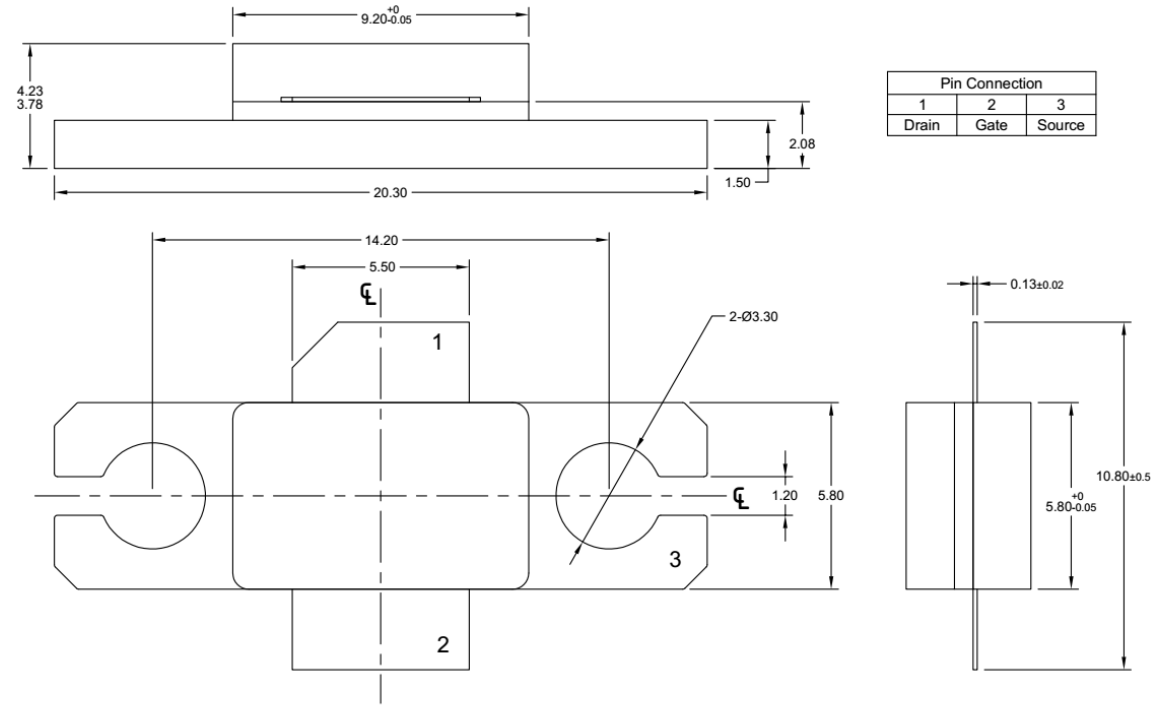
Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{GS}=-8V; I_{DS}=14mA	V_{DSS}	150			V
Gate Threshold Voltage	V_{DS} = 28V, I_D = 14 mA	V_{GS}(th)		-2.7		V
Gate Quiescent Voltage	V_{DS} =28V, I_{DS}=700mA, Measured in Functional Test	$V_{GS(Q)}$		-2.27		V

Functional Tests (In 3.4-3.6GHz Production fixture, 50 ohm system) :V_{DD} = 28 Vdc, I_{DQ} = 700 mA, f = 3600 MHz, WCDMA signal, Pout=12W

Characteristic	Symbol	Min	Typ	Max	Unit
Power Gain	Gp		15		dB
Drain Efficiency @ P_{out}	Eff		34		%
Saturated Power by CCDF test	P_{SAT}	60			W
Input Return Loss	IRL		-7		dB
Mismatch stress at all phases (Device no damage)	VSWR		10:1		Ψ

Package Outline

Flanged ceramic package; 2 leads



Unit: mm
Tolerances(unless specified): x.x ±0.1
x.xx ±0.05

OUTLINE VERSION	REFERENCE			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
PKG-GXB					10/10/2017

Figure 1. Package Outline PKG-G2E

Revision history

Table 4. Document revision history

Date	Revision	Datasheet Status
2017/6/26	V1.0	Objective Datasheet Creation
2017/7/27	V1.0	Preliminary Datasheet creation

Notice